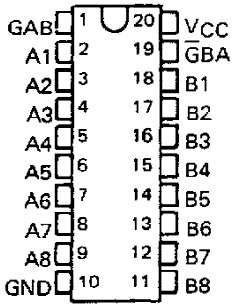
SN54LS620, SN54LS621, SN74LS620, SN74LS621, SN74LS623
OCTAL BUS TRANSCEIVERS

SDLS185 — D2537, AUGUST 1979—REVISED MARCH 1988

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- Local Bus-Latch Capability
- Hysteresis at Bus Inputs Improves Noise Margins
- Choice of True or Inverting Logic
- Choice of 3-State or Open-Collector Outputs

DEVICE	OUTPUT	LOGIC
'LS620	3-State	Inverting
'LS621	Open-Collector	True
'LS623	3-State	True

SN54LS620, SN54LS621, SN54LS622 . . . J PACKAGE
SN74LS620, SN74LS621, SN74LS623 . . . DW OR N PACKAGE
(TOP VIEW)



description

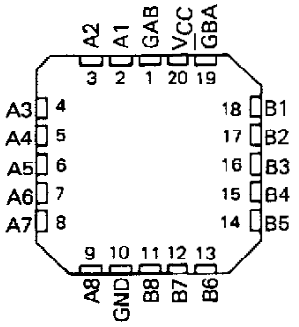
These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control function implementation allows for maximum flexibility in timing.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the enable inputs ($\overline{G}$BA and GAB).

The enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the 'LS620, 'LS621, and 'LS623 the capability to store data by simultaneous enabling of $\overline{G}$BA and GAB. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 in all) will remain at their last states. The 8-bit codes appearing on the two sets of buses will be identical for the 'LS621 and 'LS623 devices or complementary for the 'LS620.

SN54LS620, SN54LS621, SN54LS622 . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE

ENABLE INPUTS		OPERATION	
$\overline{G}$BA	GAB	'LS620	'LS621, 'LS623
L	L	$\overline{B}$ data to A bus	B data to A bus
H	H	$\overline{A}$ data to B bus	A data to B bus
H	L	Isolation	Isolation
L	H	$\overline{B}$ data to A bus, $\overline{A}$ data to B bus	B data to A bus, A data to B bus

H = high level, L = low level

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

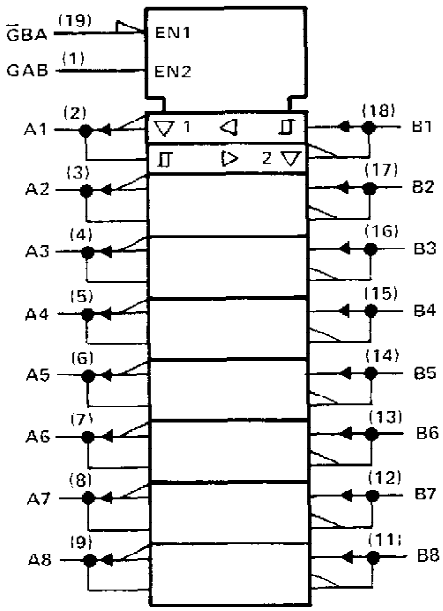
Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Off-state output voltage . . . . . 5.5 V
Operating free-air temperature range: SN54LS' . . . . . −55°C to 125°C
SN74LS' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

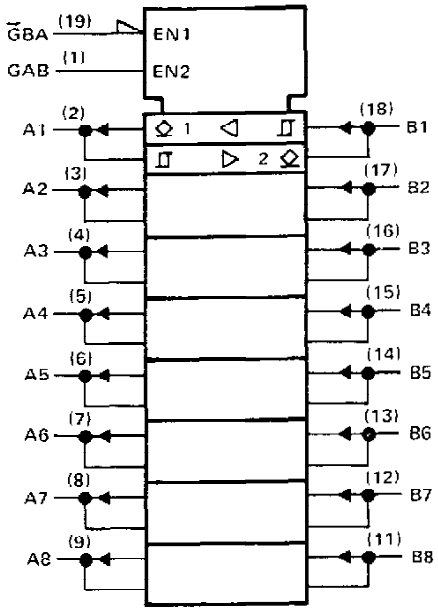
TEXAS INSTRUMENTS
POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

logic symbols†

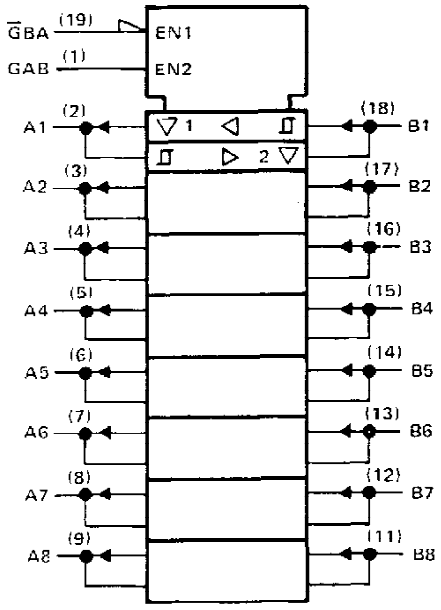
'LS620



'LS621

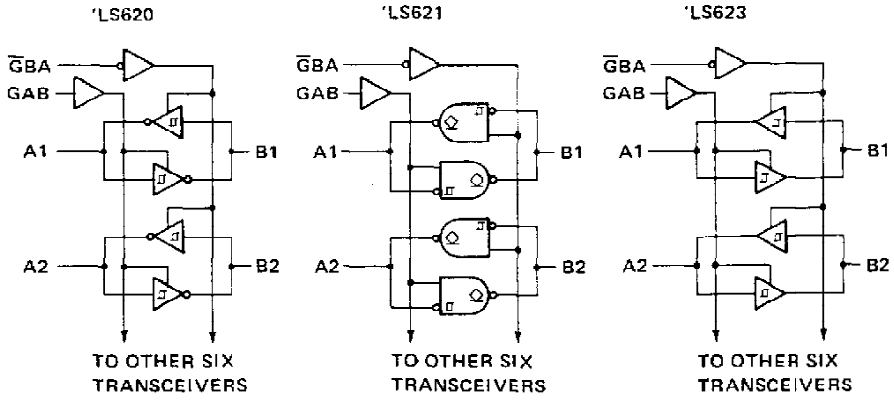


'LS623

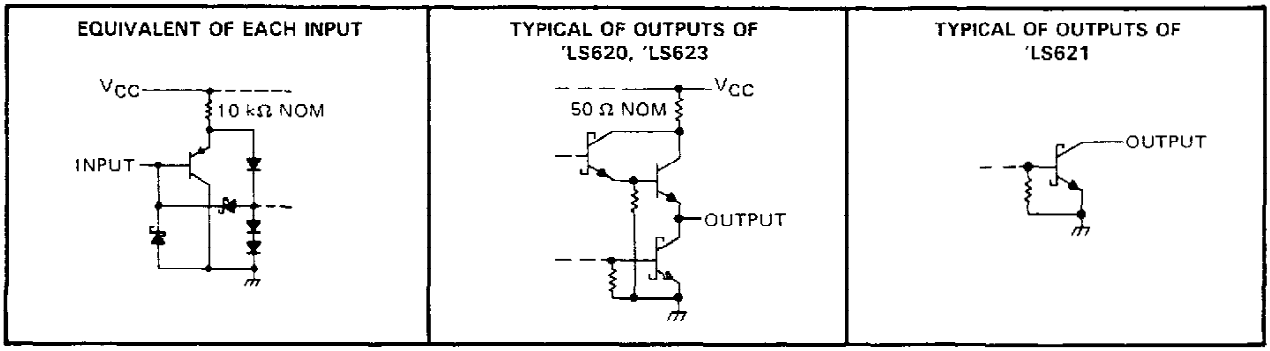


† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, and N packages.

logic diagrams (positive logic)



schematics of inputs and outputs



recommended operating conditions

PARAMETER	SN54LS620			SN74LS620 SN74LS623			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC} (see Note 1)	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−12			−15	mA
Low-level output current, I_{OL}			12			24	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

NOTE 1: Voltage values are with respect to network ground terminal.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS620			SN74LS620 SN74LS623			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.5			0.6	V
V_{IK}	Input clamp voltage		V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
	Hysteresis ($V_{T+} - V_{T-}$) A or B input		V_{CC} = MIN		0.1	0.4		0.2	0.4		V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OH} = −3 mA	2.4	3.4		2.4	3.4		V
				I_{OH} = MAX	2			2			
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 24 mA					0.35	0.5	
I_{OZH}	Off-state output current, high-level voltage applied		V_{CC} = MAX, V_O = 2.7 V	$\overline{G}$ at 2 V,			20			20	µA
I_{OZL}	Off-state output current, low-level voltage applied		V_{CC} = MAX, V_O = 0.4 V	$\overline{G}$ at 2 V,			−400			−400	µA
I_I	Input current at maximum input voltage	A or B	V_{CC} = MAX,	V_I = 5.5 V			0.1			0.1	mA
		$\overline{G}$BA or GAB		V_I = 7 V			0.1			0.1	
I_{IH}	High-level input current		V_{CC} = MAX,	V_I = 2.7 V			20			20	µA
I_{IL}	Low-level input current		V_{CC} = MAX,	V_I = 0.4 V			−0.4			−0.4	mA
I_{OS}	Short-circuit output current §		V_{CC} = MAX		−40		−225	−40		−225	mA
I_{CC}	Total supply current	Outputs high	V_{CC} = MAX,	Outputs open		48	70		48	70	mA
		Outputs low				62	90		62	90	
		Outputs at Hi-Z				64	95		64	95	

† For conditions shown as MIN or MAX use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics at V_{CC} = 5 V, T_A = 25°C

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS620			SN74LS623			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high-level output	A	B	C_L = 45 pF, R_L = 667 Ω, See Note 2		6	10		8	15	ns
		B	A			6	10		8	15	
t_{PHL}	Propagation delay time, high-to-low-level output	A	B			8	15		11	15	ns
		B	A			8	15		11	15	
t_{PZL}	Output enable time to low level	$\overline{G}$BA	A			31	40		31	40	ns
		GAB	B			31	40		31	40	
t_{PZH}	Output enable time to high level	$\overline{G}$BA	A			23	40		26	40	ns
		GAB	B			23	40		26	40	
t_{PLZ}	Output disable time from low level	$\overline{G}$BA	A	C_L = 5 pF, R_L = 667 Ω, See Note 2		15	25		15	25	ns
		GAB	B			15	25		15	25	
t_{PHZ}	Output disable time from high level	$\overline{G}$BA	A			15	25		15	25	ns
		GAB	B			15	25		15	25	

t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
t_{PZH} = Output enable time to high level
t_{PZL} = Output enable time to low level
t_{PHZ} = Output disable time from high level
t_{PLZ} = Output disable time from low level

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

PARAMETER	SN54LS621			SN74LS621			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC} (see Note 1)	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, V_{OH}			5.5			5.5	V
Low-level output current, I_{OL}			12			24	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

NOTE 1: Voltage values are with respect to network ground terminal.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS621			SN74LS621			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.5			0.6	V
V_{IK}	Input clamp voltage		V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
	Hysteresis ($V_{T+} - V_{T-}$) A or B input		V_{CC} = MIN		0.1	0.4		0.2	0.4		V
I_{OH}	High-level output current		V_{CC} = MIN, V_{IL} = V_{IL} max,	V_{IH} = 2 V, V_{OH} = 5.5 V			100			100	μA
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 24 mA					0.35	0.5	
I_I	Input current at maximum input voltage	A or B	V_{CC} = MAX,	5.5 V			0.1			0.1	mA
		GAB or $\overline{GBA}$		V_I = 7 V			0.1			0.1	
I_{IH}	High-level input current		V_{CC} = MAX,	V_I = 2.7 V			20			20	μA
I_{IL}	Low-level input current		V_{CC} = MAX,	V_I = 0.4 V			−0.4			−0.4	mA
I_{CC}	Total supply current	Outputs high	V_{CC} = MAX,	Outputs open		48	70		48	70	mA
		Outputs low				62	90		62	90	

†For conditions shown as MIN or MAX use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS621			UNIT
					MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high-level output	A	B	C_L = 45 pF, R_L = 667 Ω, See Note 2		17	25	ns
		B	A			17	25	
t_{PHL}	Propagation delay time, high-to-low-level output	A	B			16	25	ns
		B	A			16	25	
t_{PLH}	Output disable time from low level	$\overline{GBA}$	A			23	40	ns
		GAB	B			25	40	
t_{PHL}	Output enable time from high level	$\overline{GBA}$	A			34	50	ns
		GAB	B			37	50	

t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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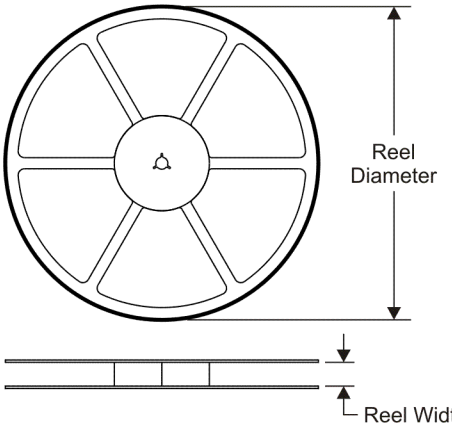
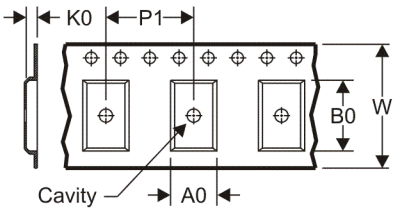
TAPE AND REEL INFORMATION

REEL DIMENSIONS

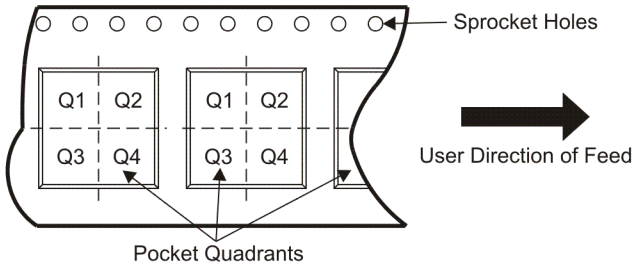


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

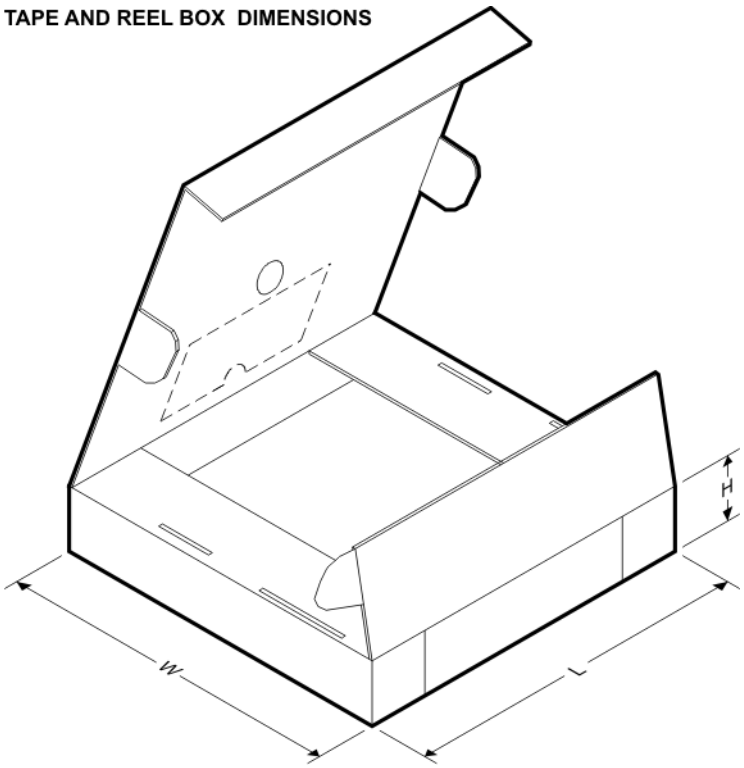
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS623DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LS623NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS623DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LS623NSR	SO	NS	20	2000	346.0	346.0	41.0

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS623N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS623N	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

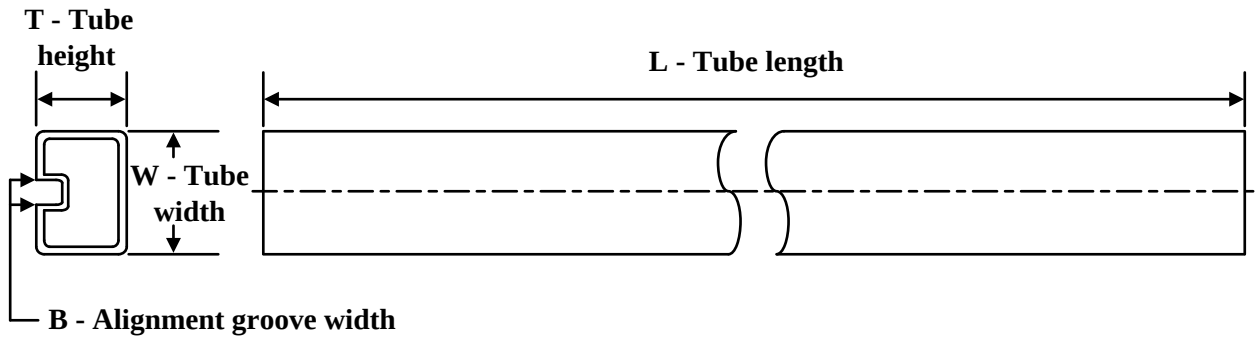
(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TUBE



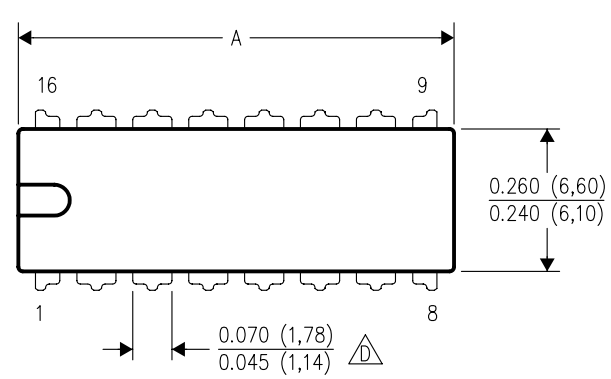
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LS623N	N	PDIP	20	20	506	13.97	11230	4.32

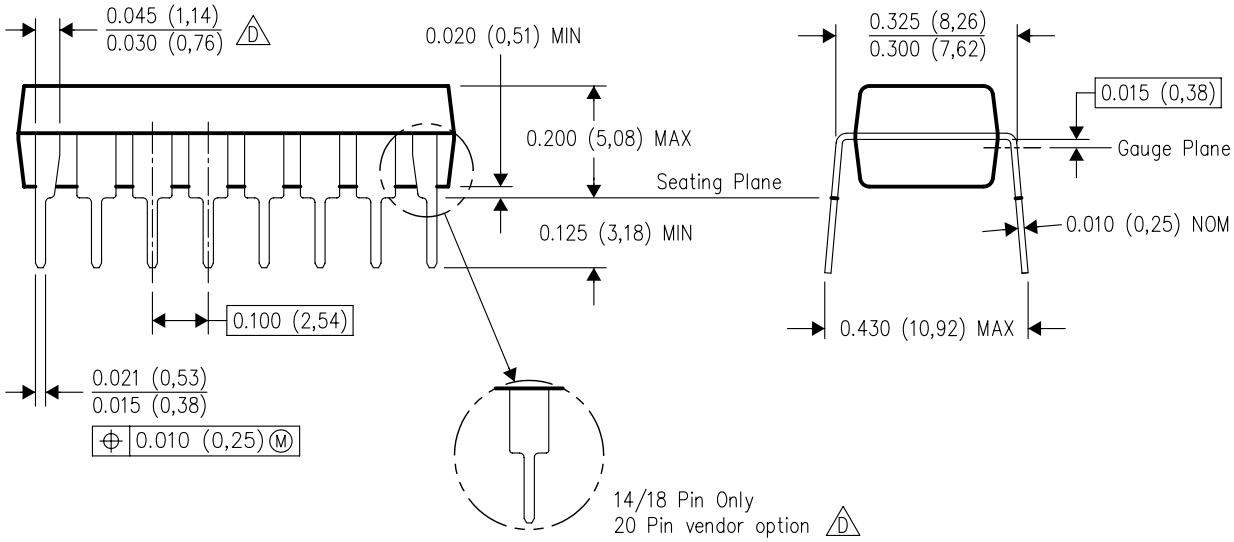
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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